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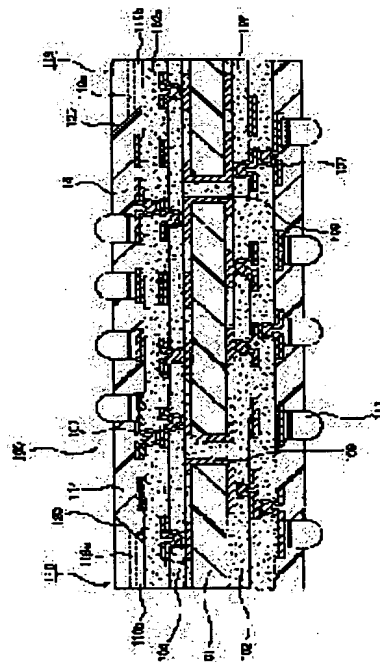
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## (54) MULTILAYER PRINTED CIRCUIT BOARD

(57)Abstract:

**PROBLEM TO BE SOLVED:** To provide a multilayer printed circuit board which can transmit both an optical signal and an electric signal, and contribute to the miniaturization of terminal equipment for an optical communication.

**SOLUTION:** In the multilayer printed circuit board in which a conductor circuit and an inter-layer a resin insulation layer are laminated on both sides of a substrate and a solder resist layer is formed in the outermost layer, an organic optical waveguide is formed in part of the solder resist layer.



## LEGAL STATUS

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